



#### Single-Event Effects Induced by Two-Photon-Absorption:

#### **Overview and Current Status**

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#### **Outline**

- Laser-Induced Single-Event Effects (SEEs)
- The Two-Photon Absorption (TPA)
  SEE Experiment
- 3-D Mapping of Single-Event Transients (SETs)
  in the LM124
- Backside "Through-Wafer" Carrier Injection
- Conclusions



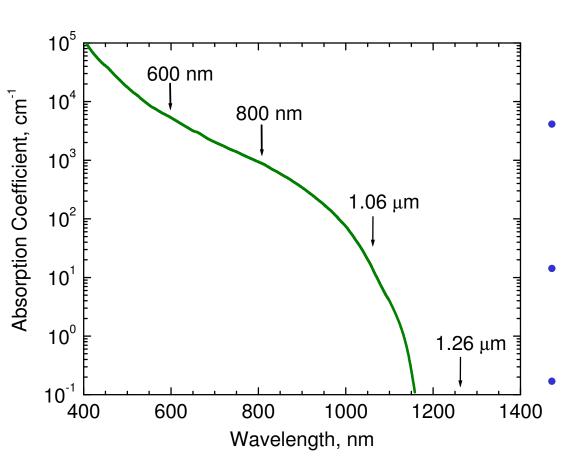


#### **Pulsed Picosecond Laser**

- Indispensable tool for SEE characterization
- Above-band gap pulsed laser can inject:
  - a well-characterized quantity of charge
  - in a well-defined location
  - at a well-defined time
  - with a well-defined charge-deposition profile







- Because the laser pulse wavelength is sub-bandgap the material is *transparent* to the optical pulse
- Carriers are generated by nonlinear absorption at high pulse irradiances by the simultaneous absorption of two photons
- Carriers are highly concentrated in the high irradiance region near the focus of the beam
  - Because of the lack of exponential attenuation, carriers can be injected at any depth in the semiconductor material
- This permits 3-D mapping and backside illumination





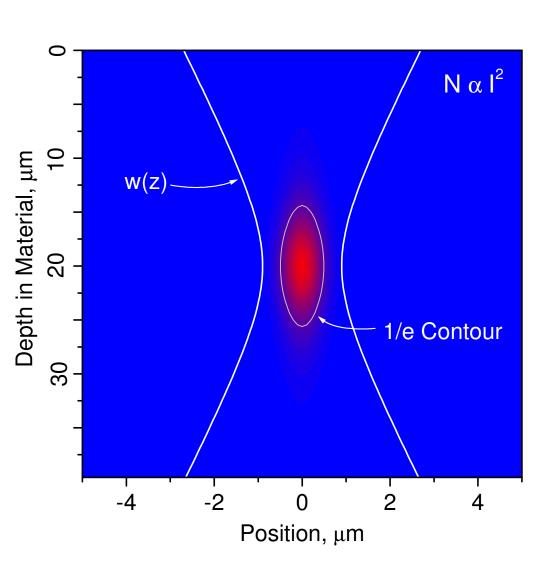
#### Carrier generation equation:

$$\frac{dN(r,z)}{dt} = \frac{\alpha I(r,z)}{\hbar \omega} + \frac{\beta_2 I^2(r,z)}{2\hbar \omega}$$

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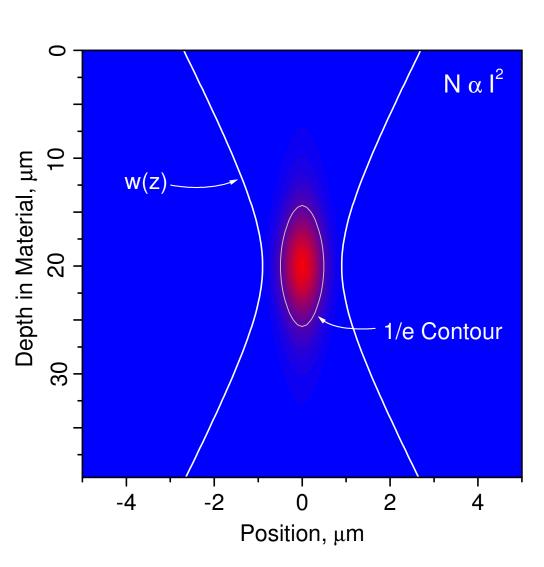




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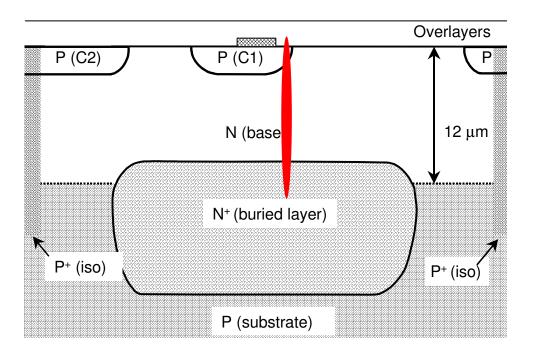




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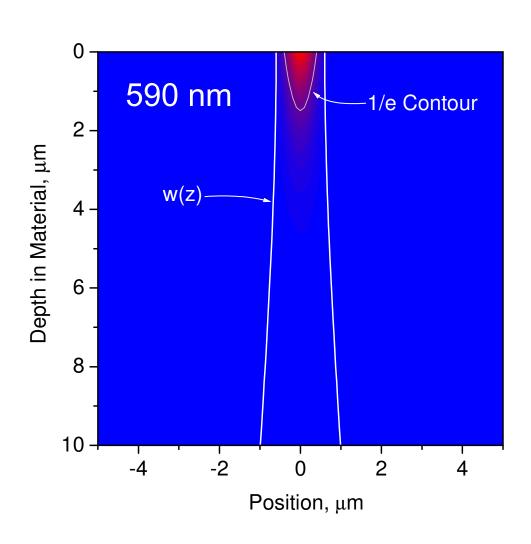




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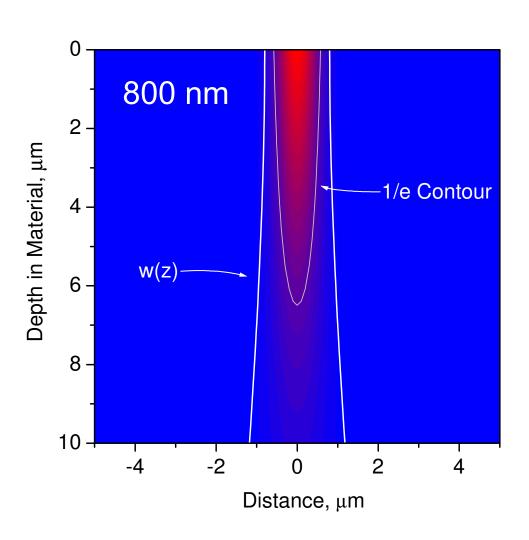






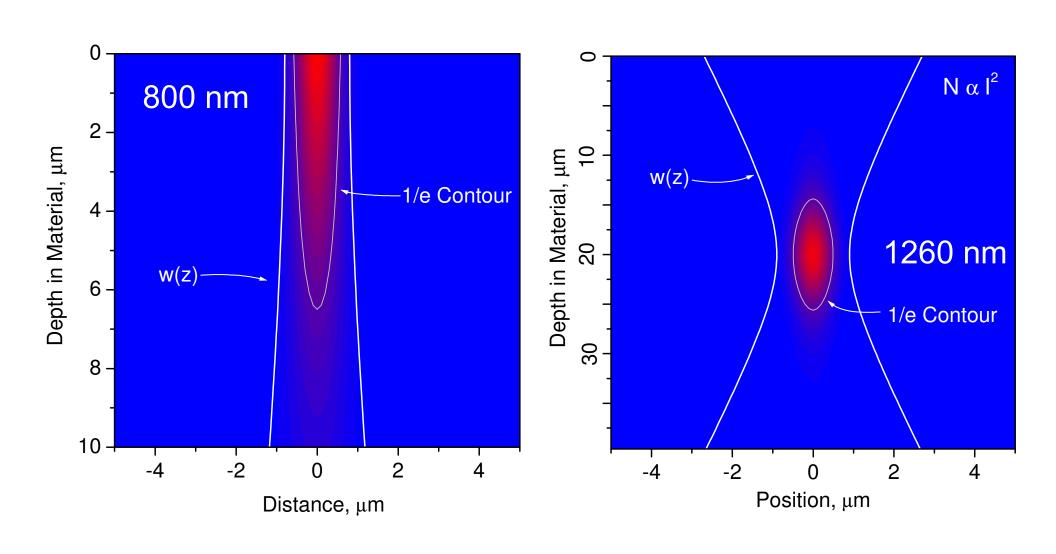














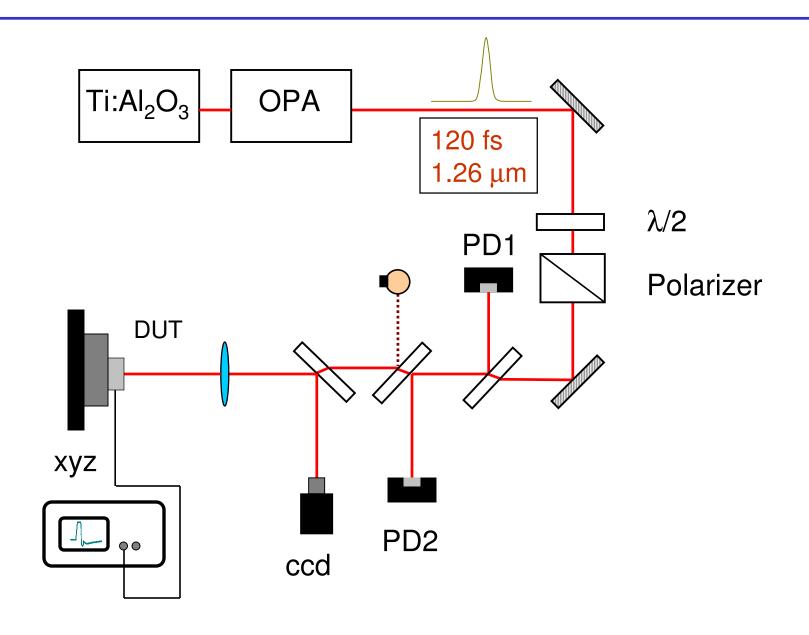


#### **COMPLEMENTARY TECHINQUE**

- Not intended to replace "conventional" (above band gap) pulsed laser
- Not intended to replace heavy-ion irradiation
- WILL NOT replace these tools
- Is another "Tool" in our "SEE Toolbox"





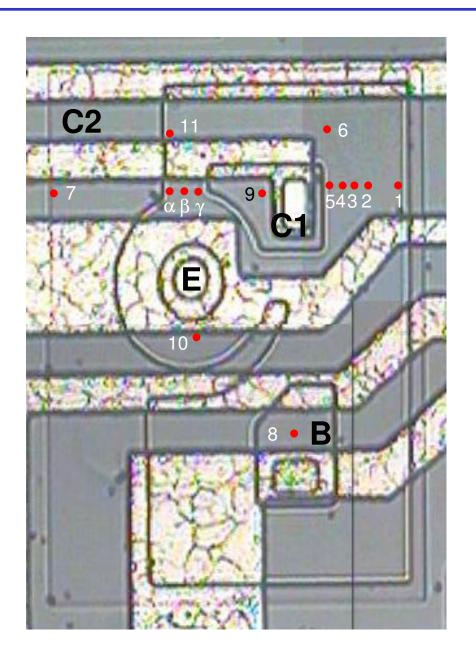






# **Three-Dimensional Mapping of SEE Sensitivity**

(LM124 Q20: General Characteristics)

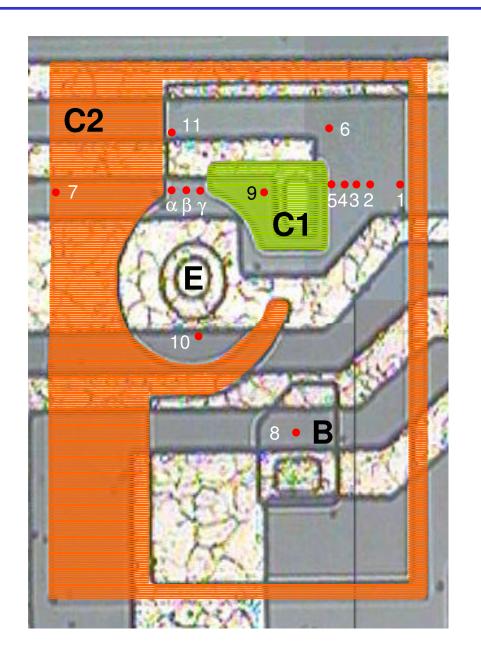






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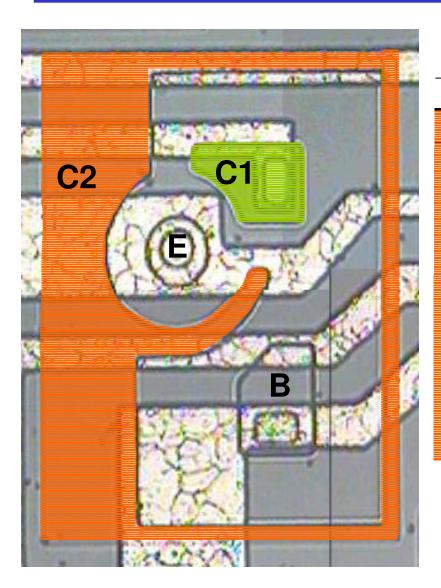


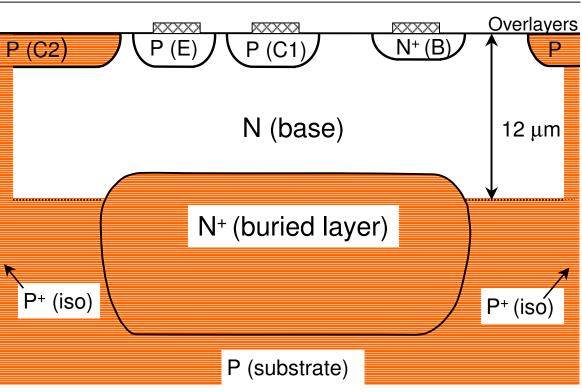




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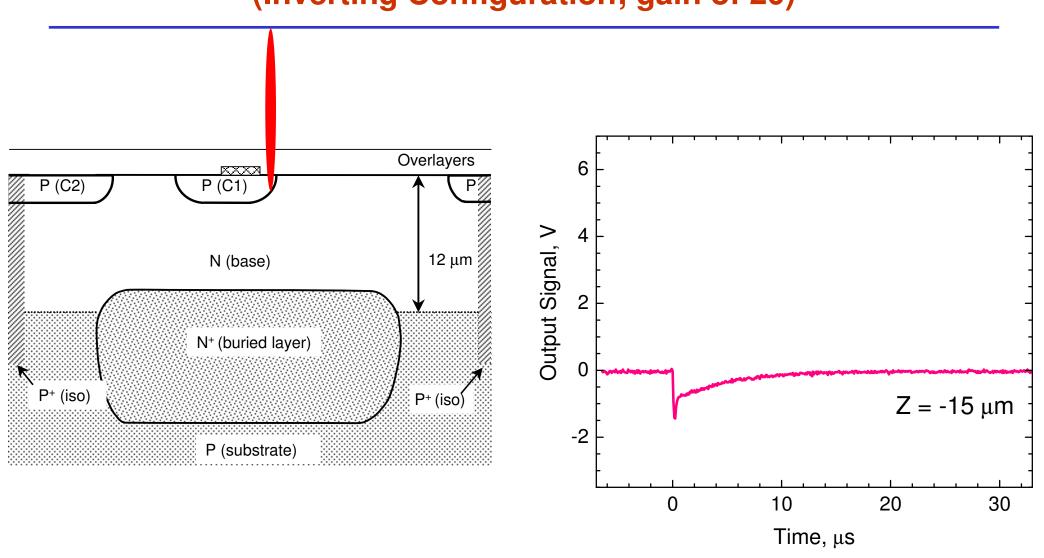
(LM124 Q20: General Characteristics)





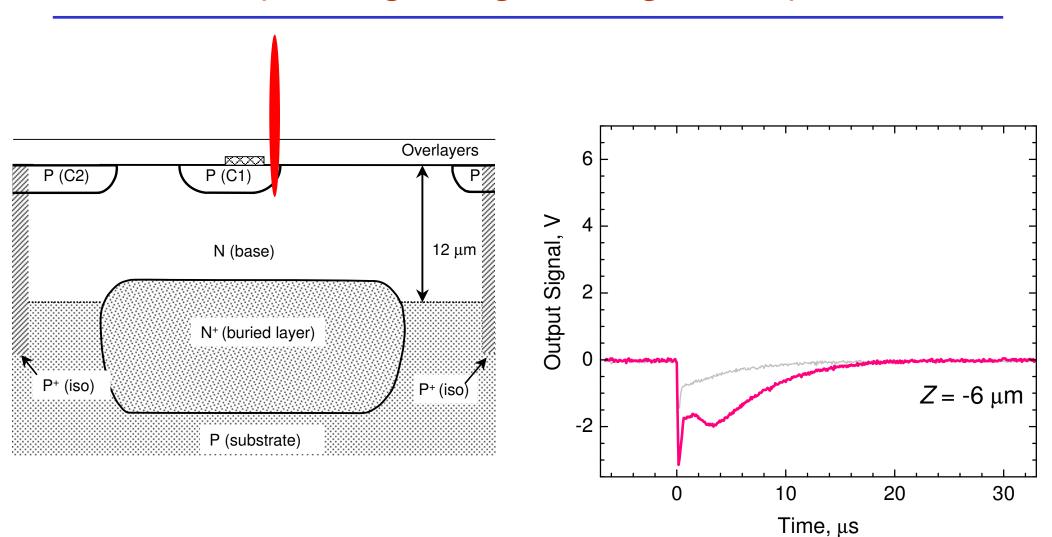






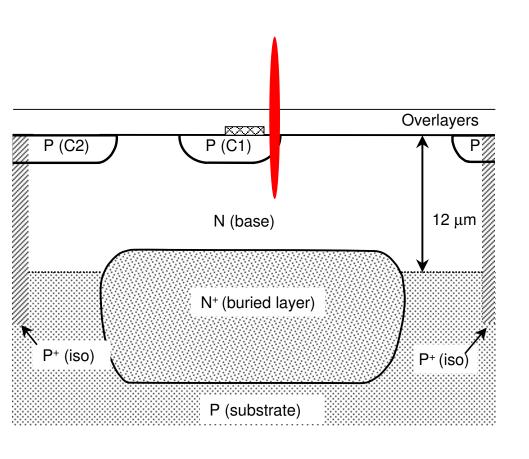


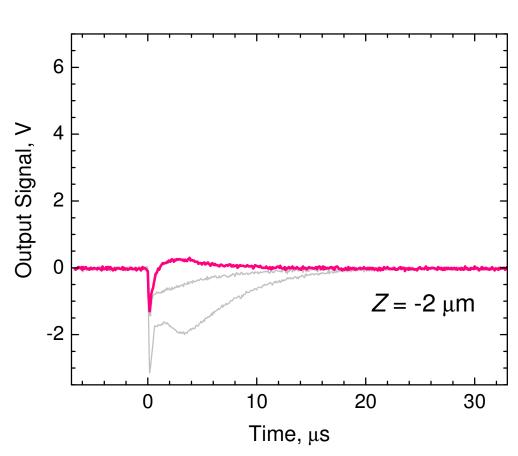






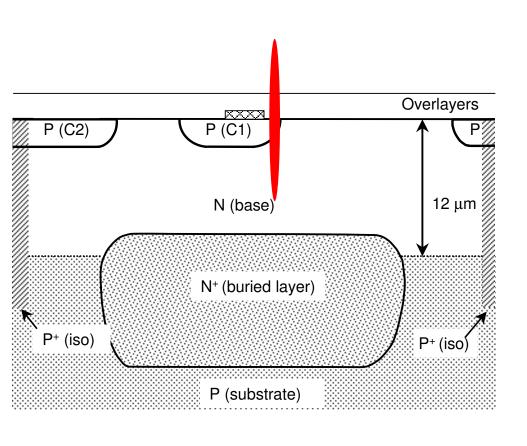


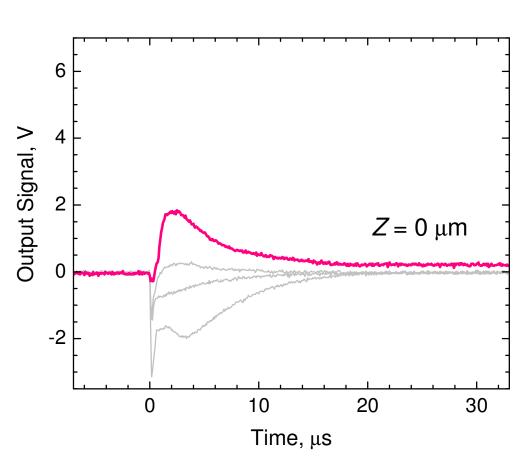






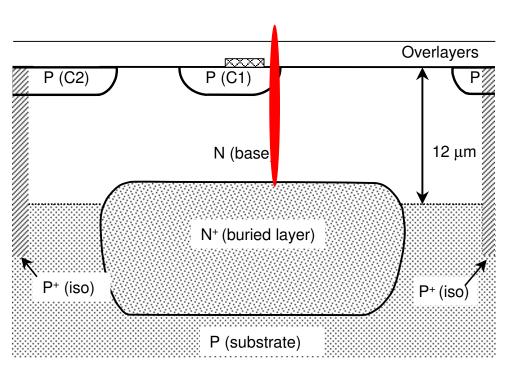


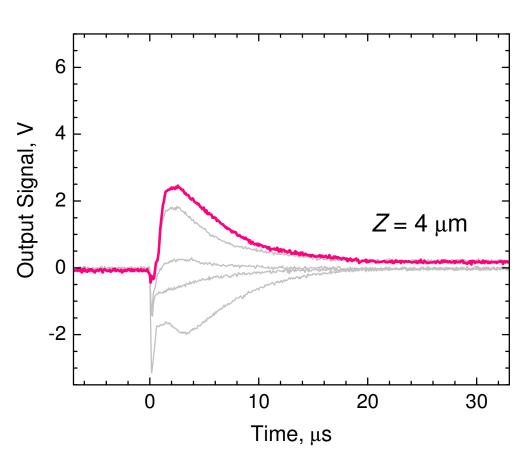






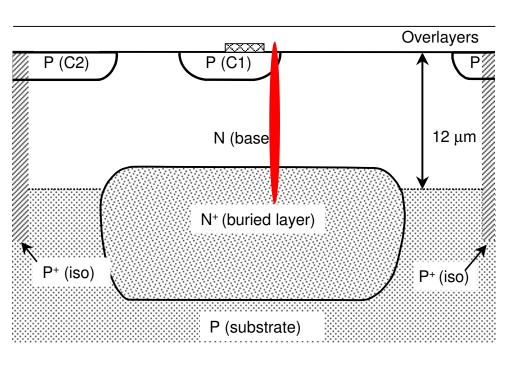


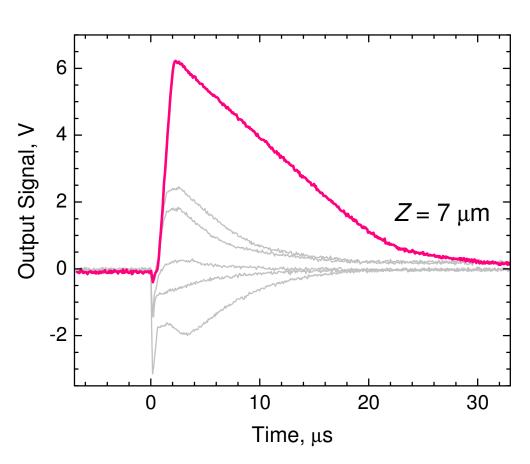






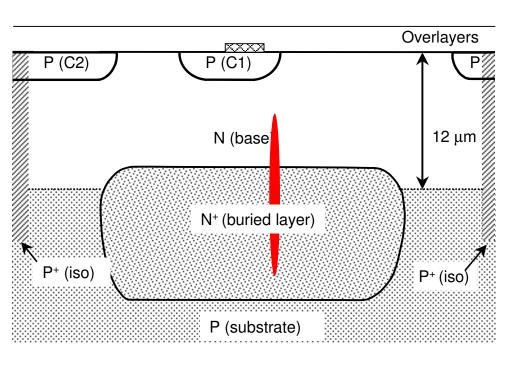


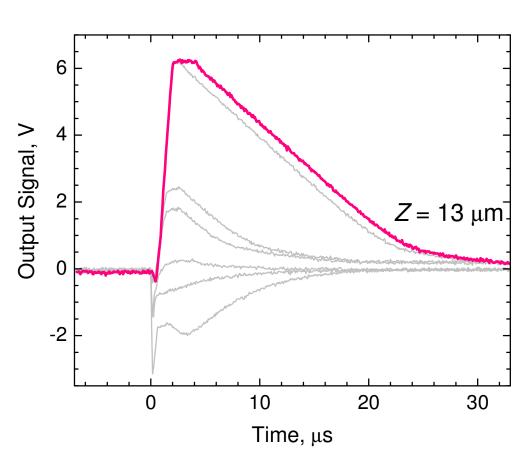






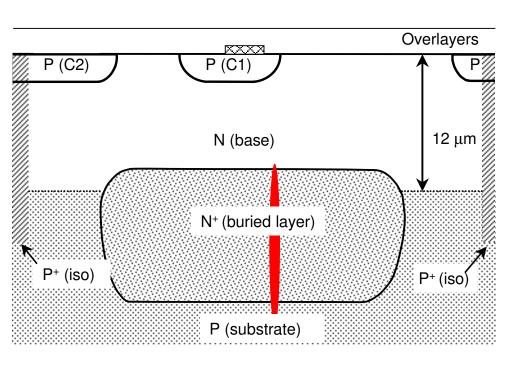


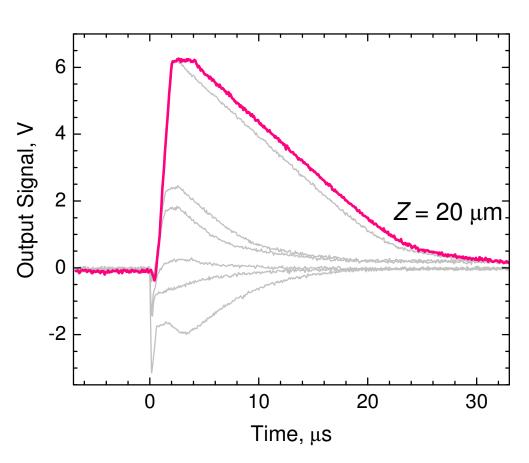






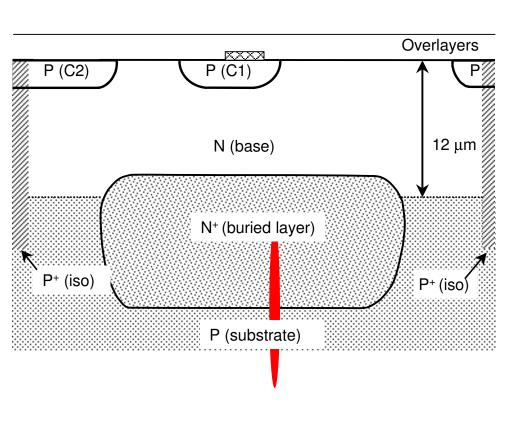


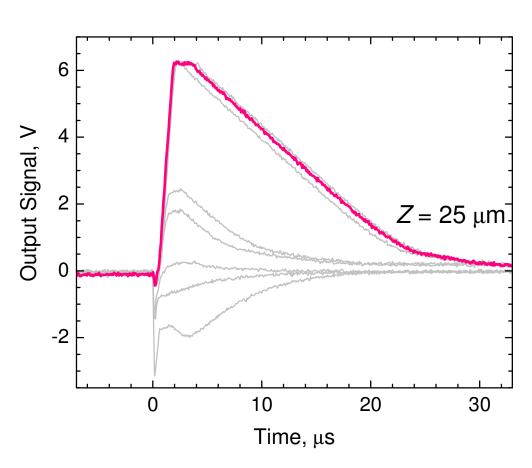






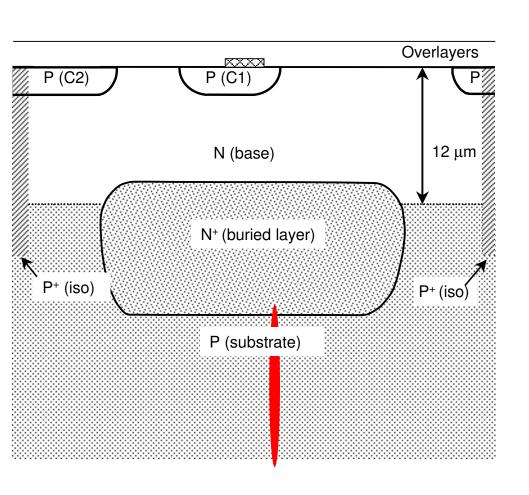


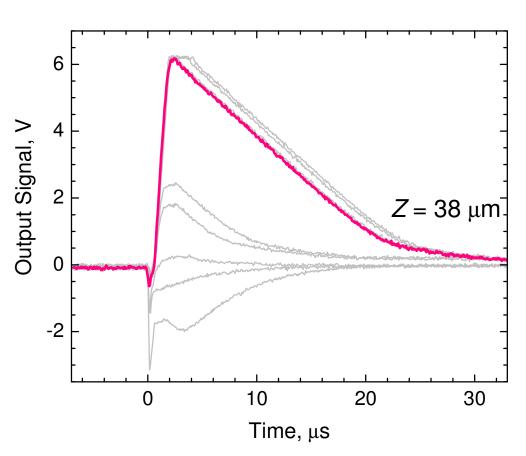






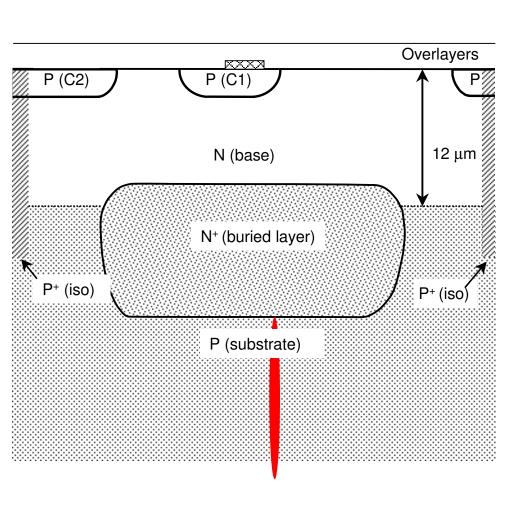


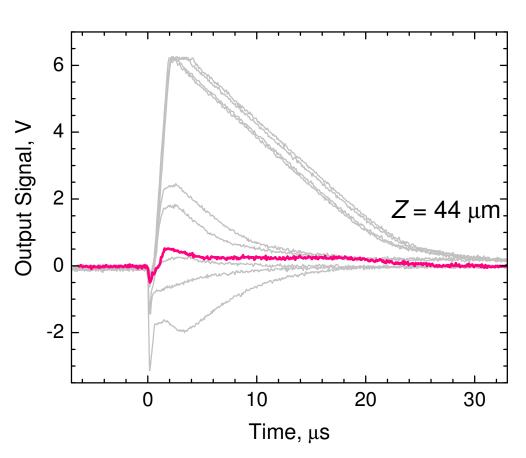






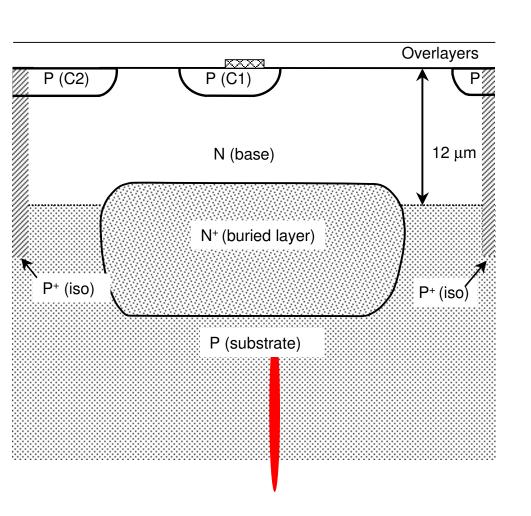


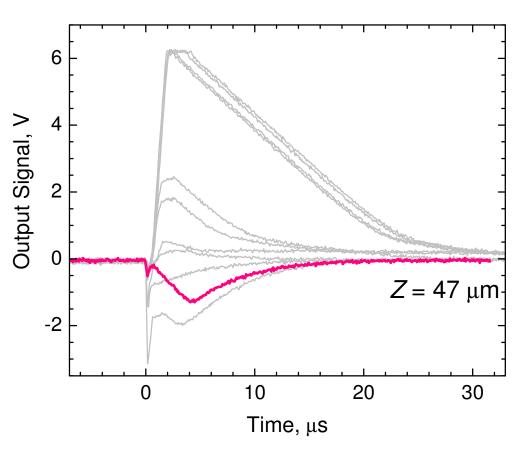






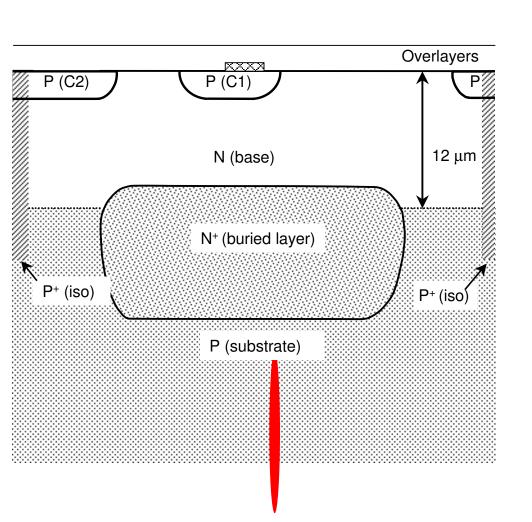


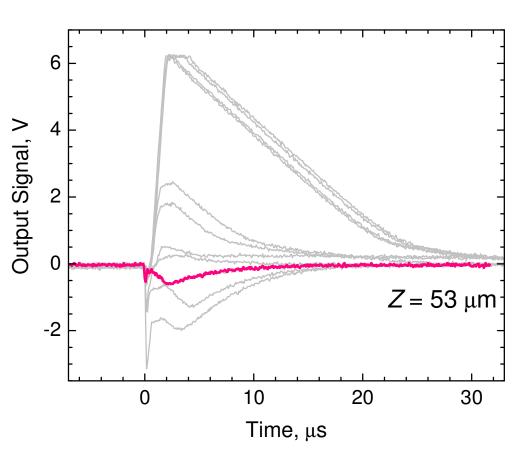








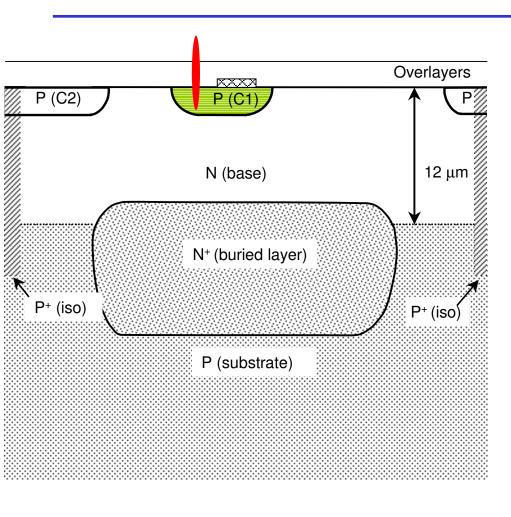


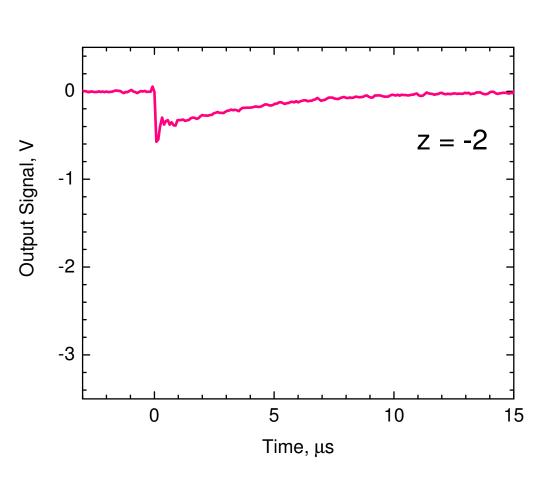






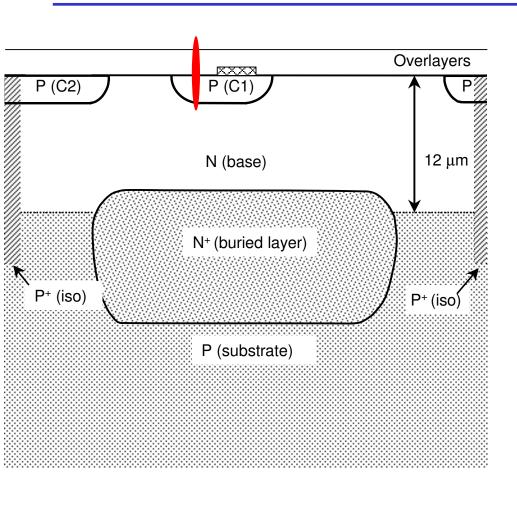
# "Z" Dependence: LM124 Q20 TPA Low Power Measurements

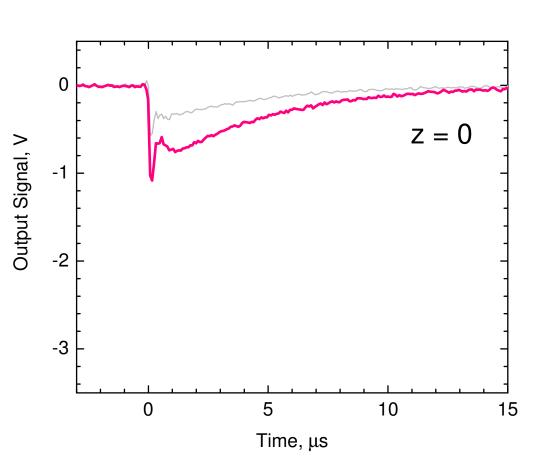






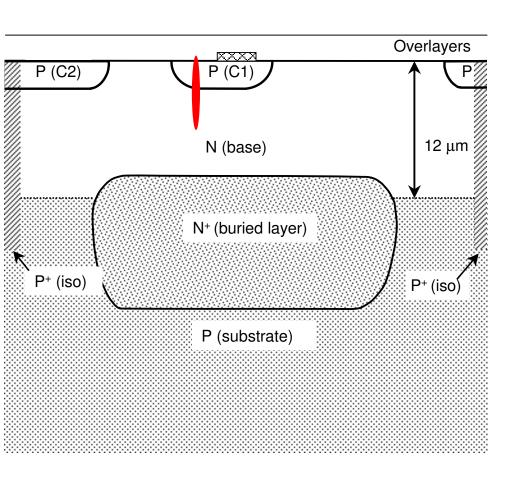


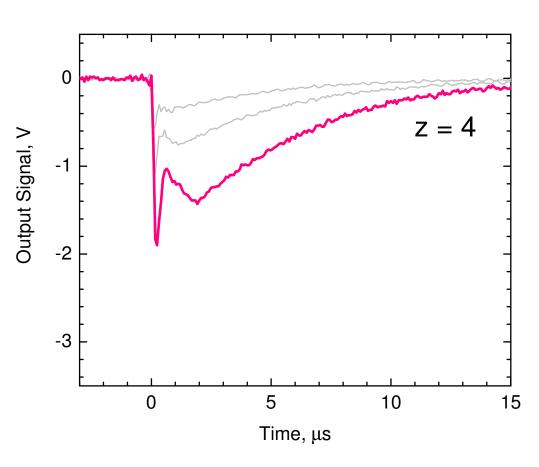






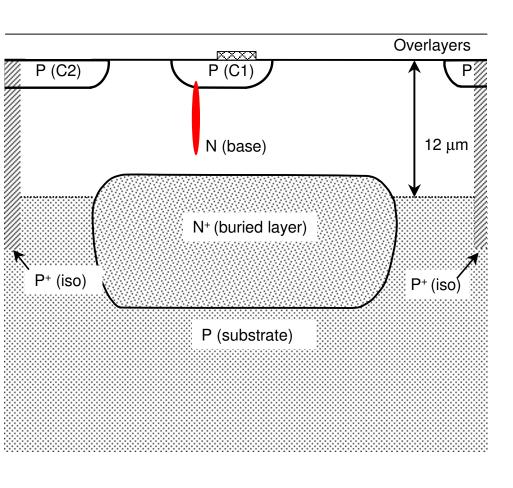


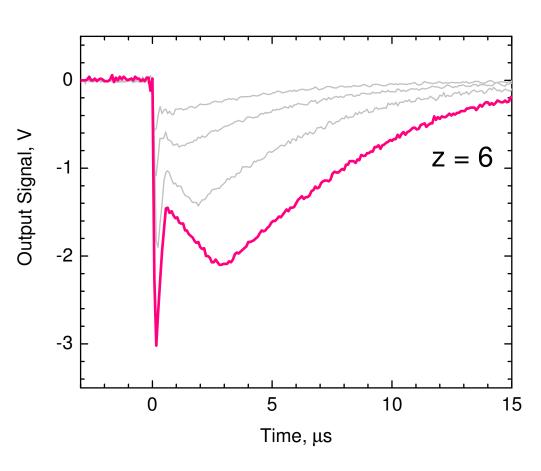






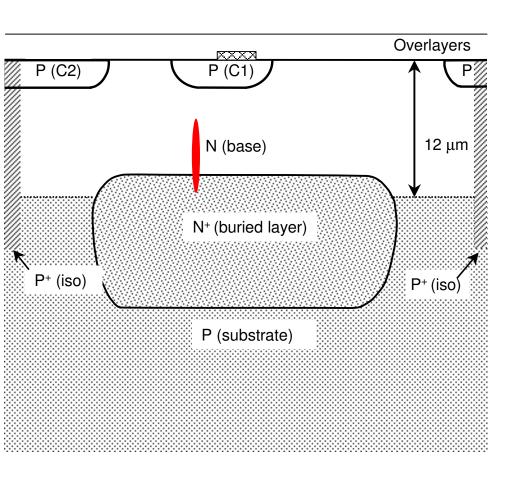


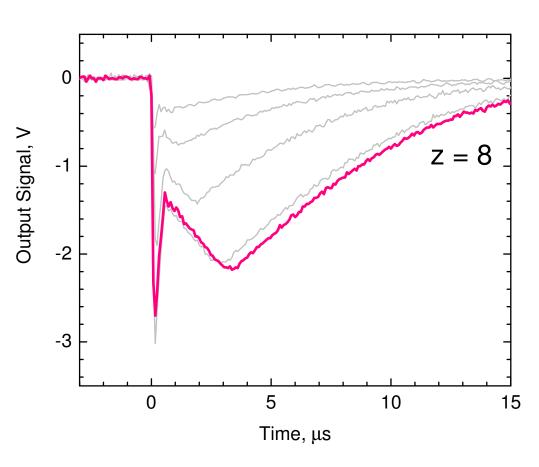






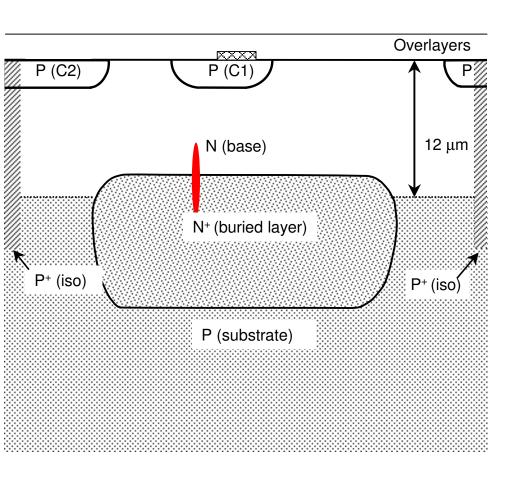


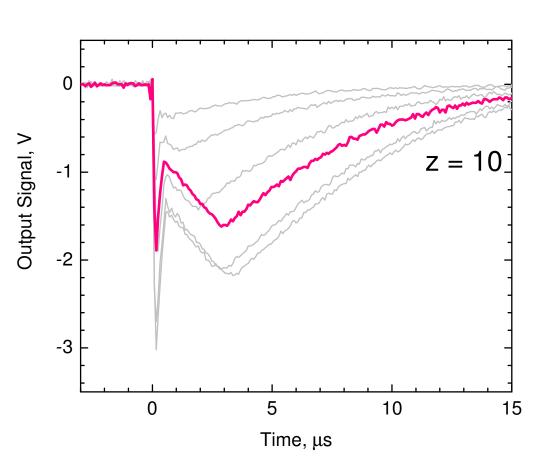






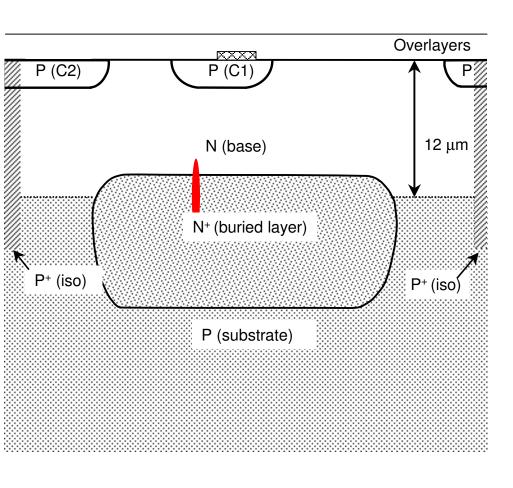


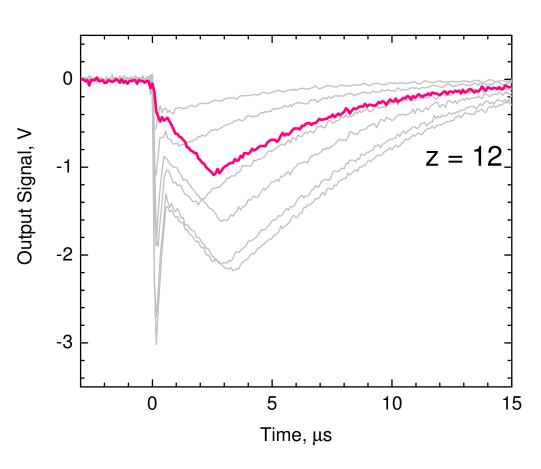










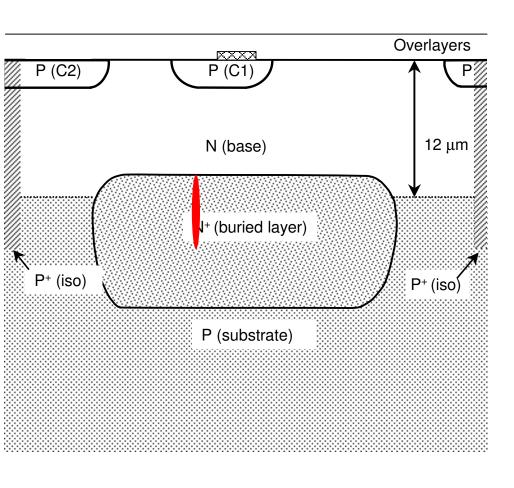


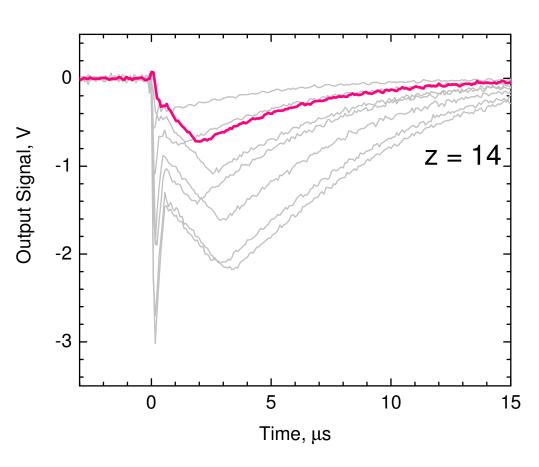




### "Z" Dependence: LM124 Q20 TPA: Low Power

(Inverting Configuration; gain of 20)



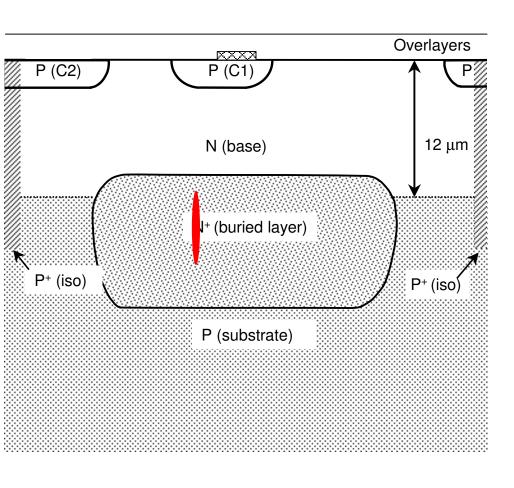


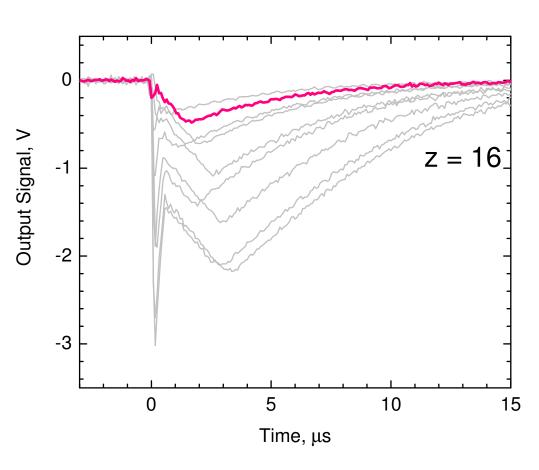




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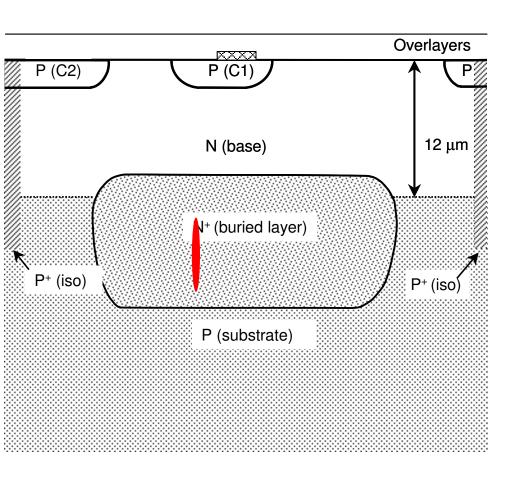


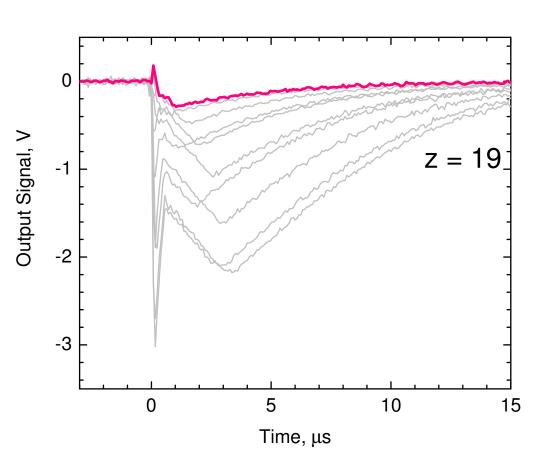




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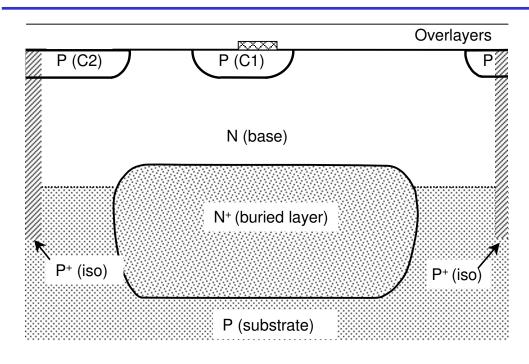
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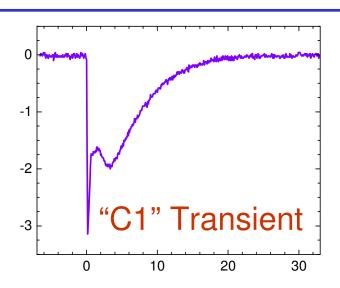


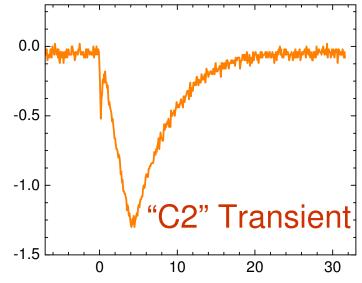


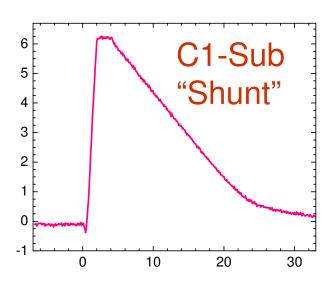






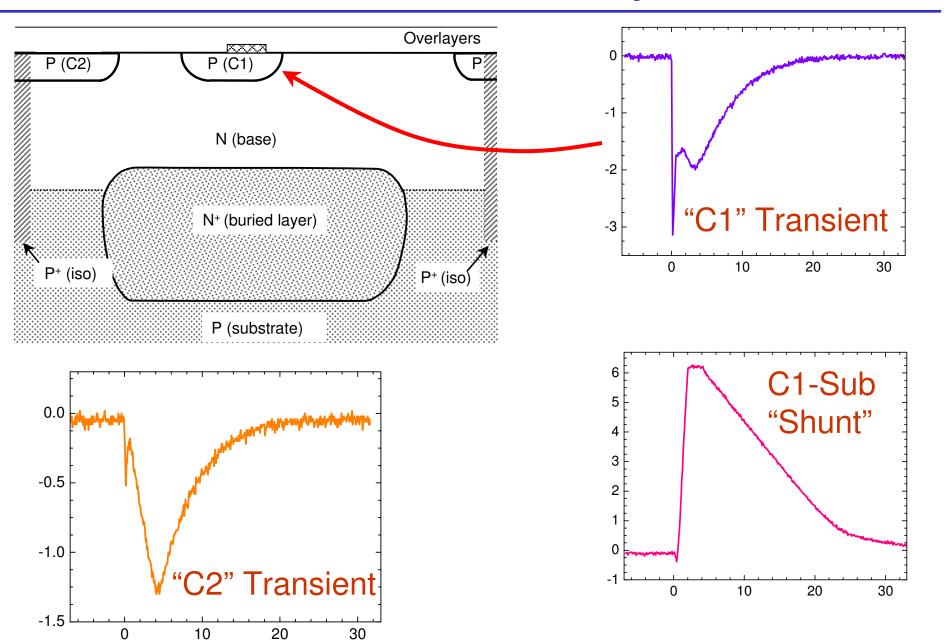






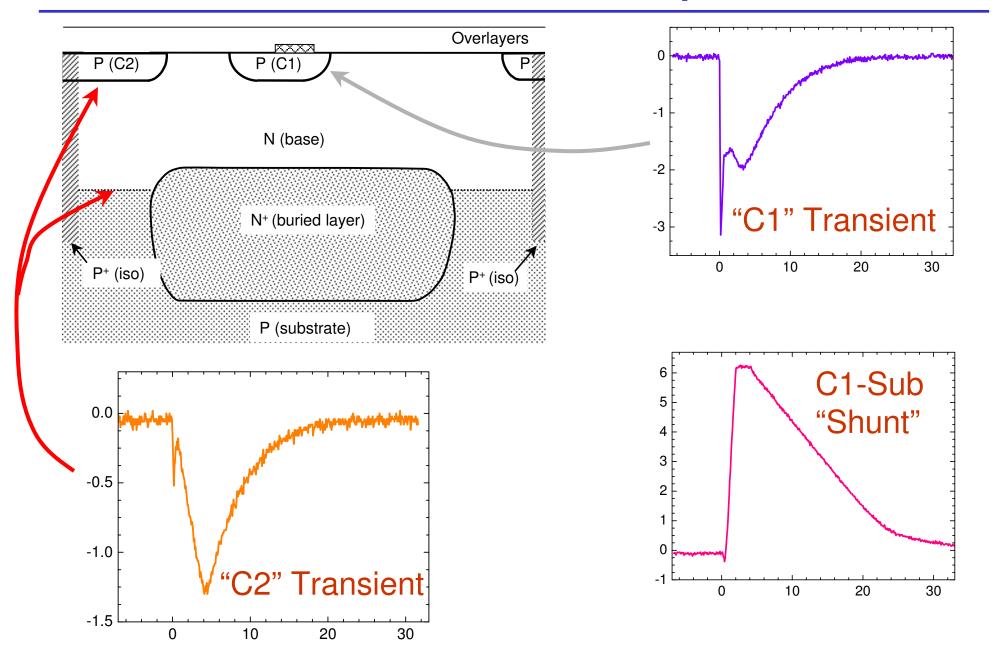






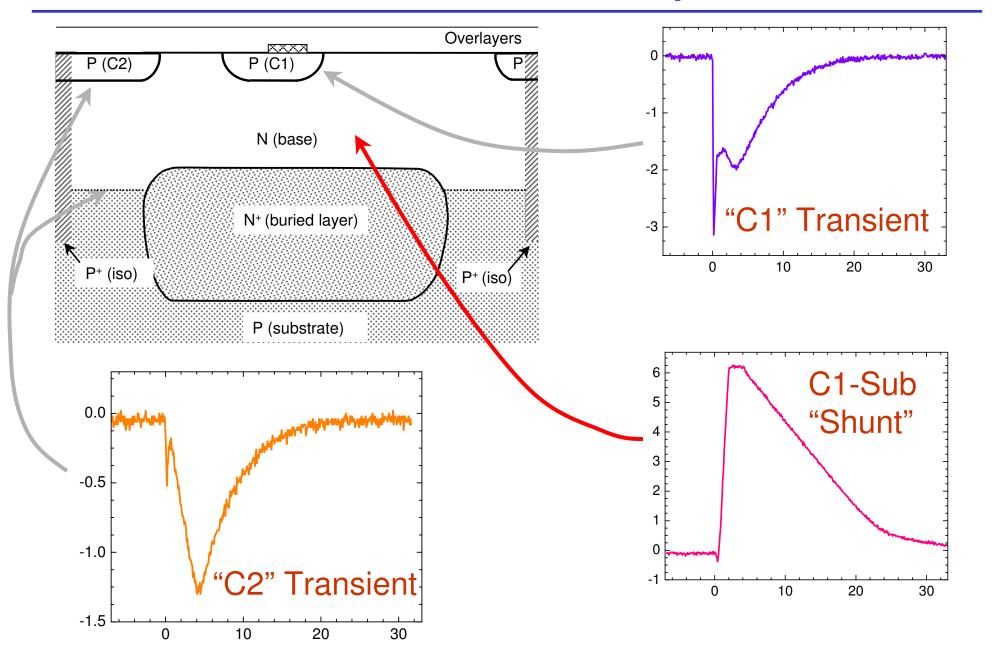








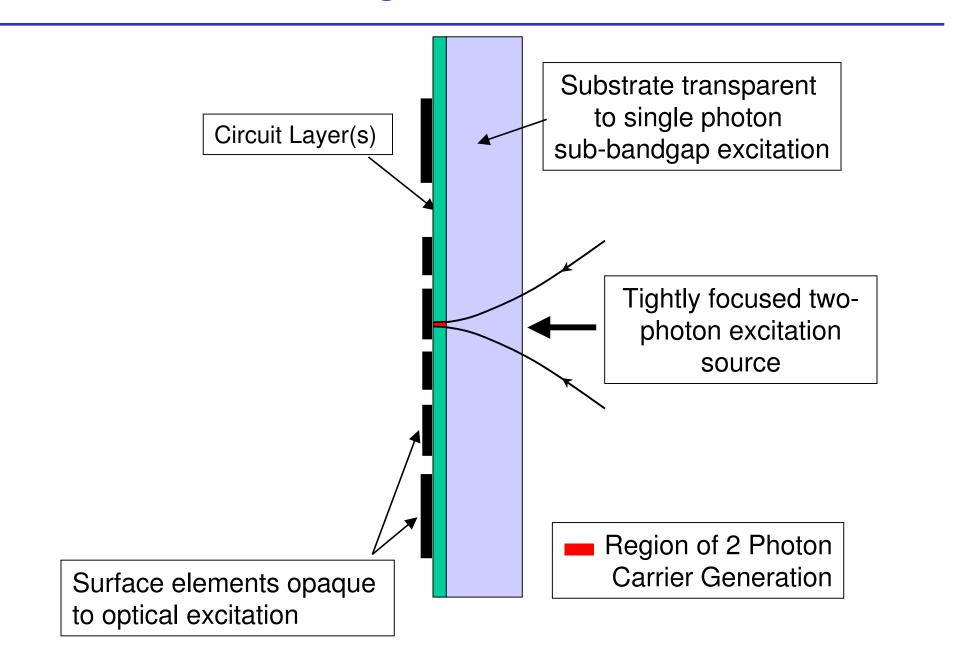








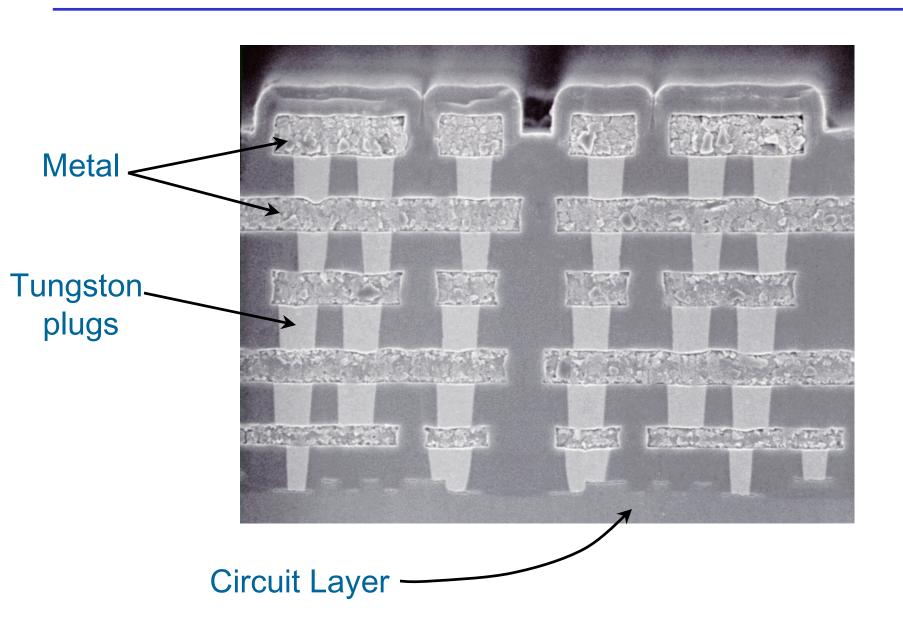
### **Backside "Through-Wafer" TPA Illumination**







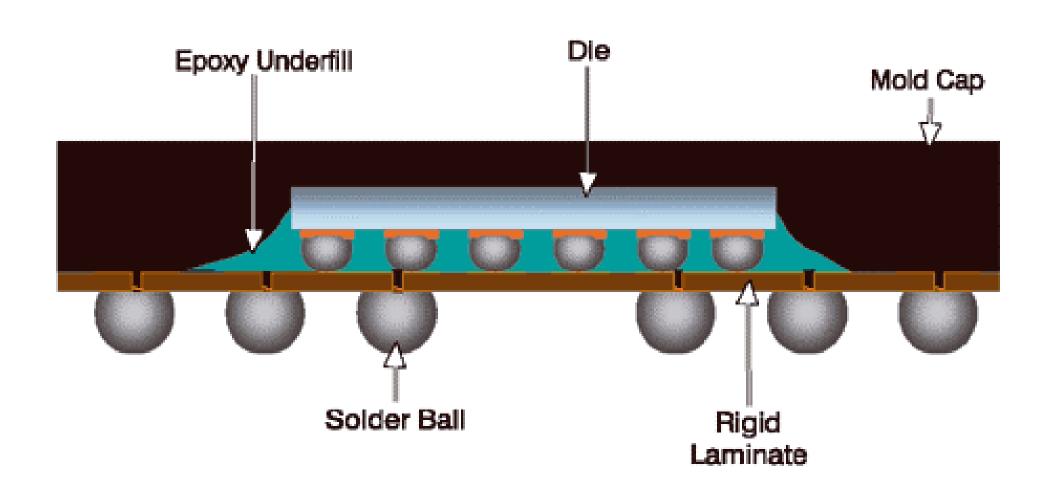
### Cross Section of Modern Device







## Schematic Flip Chip Cross Section

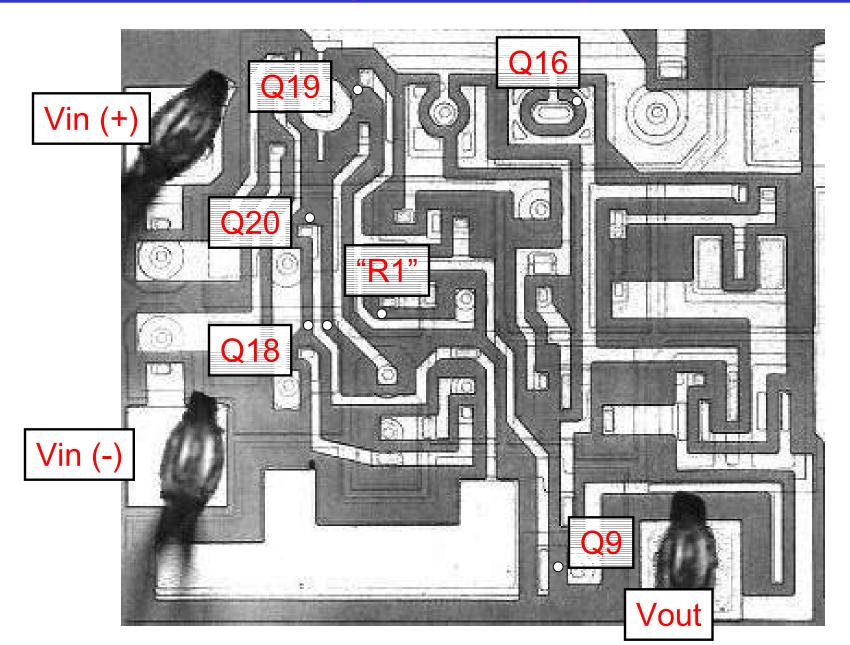






## Backside "Through-Wafer" TPA Illumination

LM124 Operational Amplifier

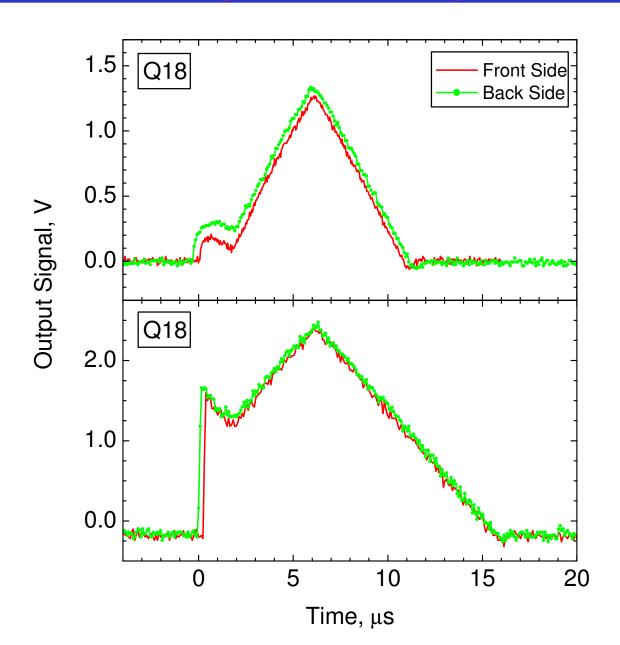






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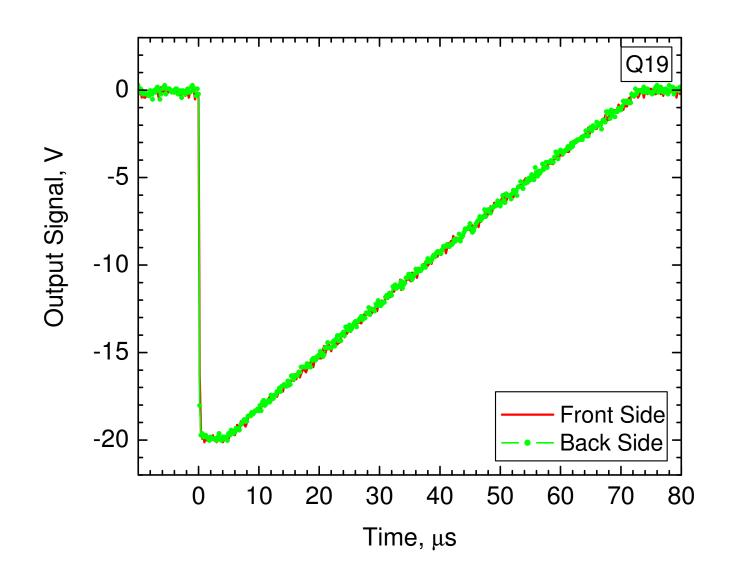
### LM124 Operational Amplifier







### Backside "Through-Wafer" TPA Illumination LM124 Operational Amplifier







# Backside "Through-Wafer" TPA Illumination SEU in Flip Chip SRAM

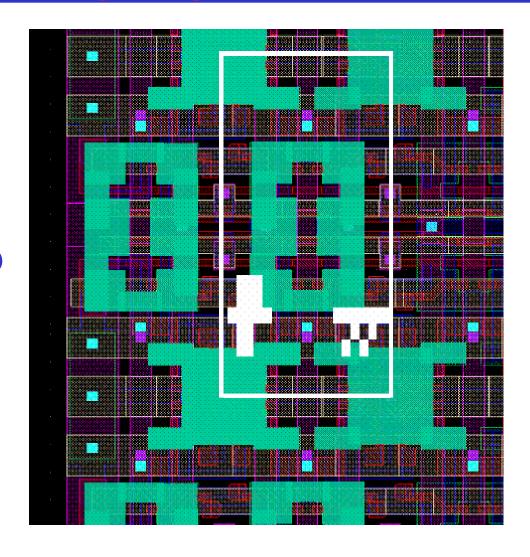
- Issues
  - through-wafer imaging
    - InGaAs FPA
  - highly-doped substrate
    - linear loss from free-carrier absorption
    - attenuates IR beam
    - attenuates illumination light
    - wafer <u>thinned</u> to minimize absorption
- <u>Results</u>: SEUs successfully injected in SRAM by TPA at well characterized locations





# **Backside "Through-Wafer" TPA Illumination SEU in Flip Chip SRAM Test Structure**

**2D SEU Map** 







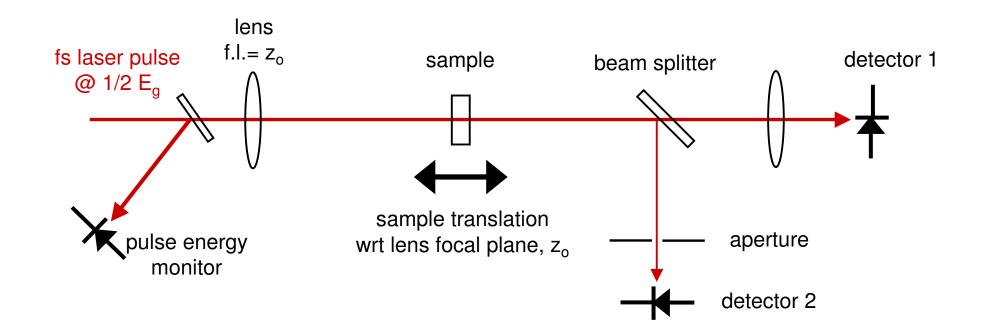
#### **Conclusions**

- The two-photon absorption method represents a novel approach to SEE evaluation with unique capabilities not exhibited by other techniques
- The present work demonstrates the utility of the nonlinear-optical TPA approach as a method for injecting carriers into the active regions of devices using both top-side and through-wafer, backside irradiation
- The use of backside irradiation eliminates interference from the metallization layers, and circumvents many of the issues associated with testing flip-chip-mounted parts
- The first experimental demonstrations of the through-wafer, backside, two-photon-induced single-event effects technique are presented





### Nonlinear Optical Measurements: Z-scans



Ultrashort laser pulse induces nonlinear lensing in sample:

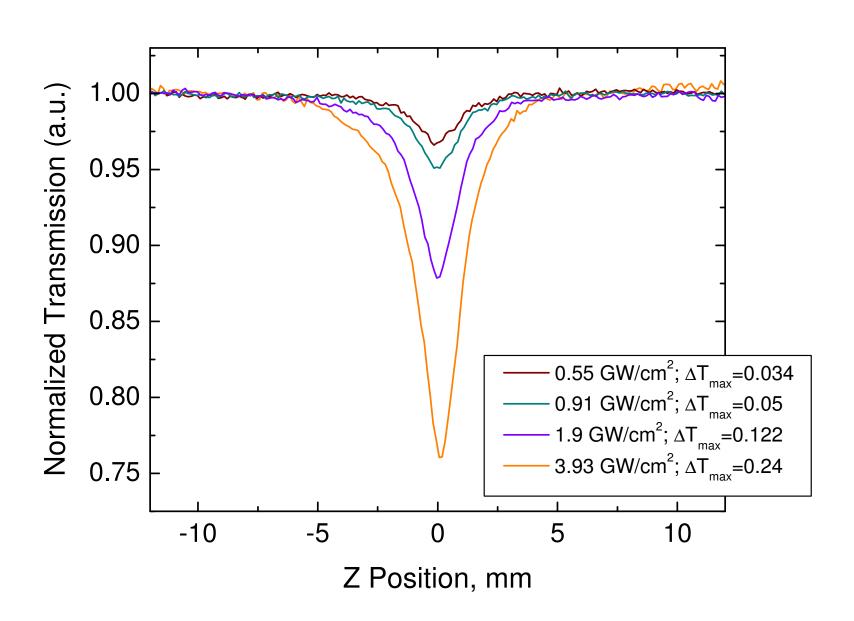
$$\Delta n(r,t) = n_2 I(r,z)$$





### **Open Aperture Z-Scan Measurement of TPA**

Antimony-Doped Silicon (0.02  $\Omega$ -cm)







### **Open Aperture Z-Scan Measurement of TPA**

Antimony-Doped Silicon (0.02  $\Omega$ -cm)

